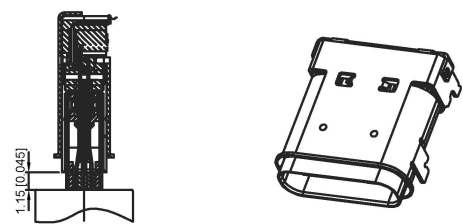
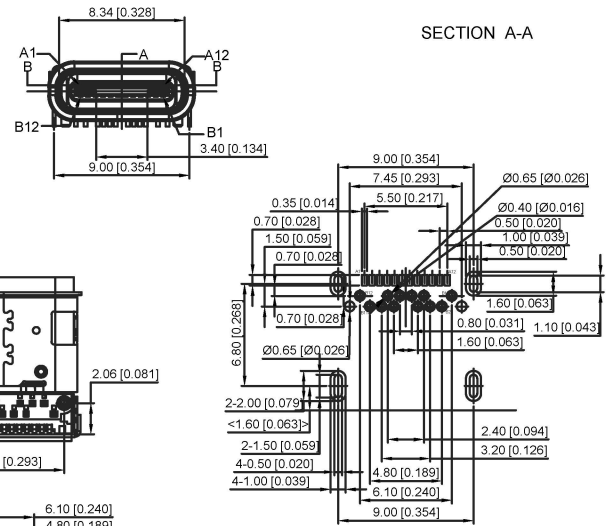
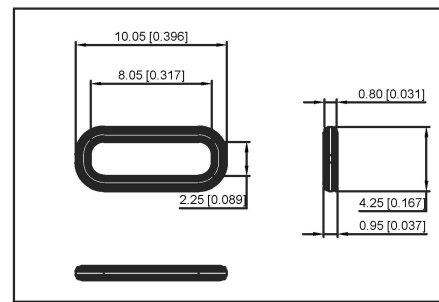


Pin	Signal Name	Mating Sequence	Pin	Signal Name	Mating Sequence
A1	GND	First	B12	GND	First
A5	SS1xp1	Second	B11	SS1xp1	Second
A5	SS1n1	Second	B10	SS1n1	Second
A4	Vas	First	B9	Vas	First
A5	CC1	Second	B8	SB12	Second
A6	bp1	Second	B7	bp2	Second
A7	bn1	Second	B6	bp2	Second
A8	SB11	Second	B5	CC2	Second
A9	Vas	First	B4	Vas	First
A10	SS1xp2	Second	B3	SS1n2	Second
A11	SS1xp2	Second	B2	SS1xp2	Second
A12	GND	First	B1	GND	First
SHELL	GND	SHELL	GND	SHELL	GND



Material
 Housing Material: High temperature thermoplastic
 Contact Terminal: High Grade Copper Alloy
 Metallic Shell: Stainless Steel
 Cover Shell: Iron
 Inner Ground Cover Shell: Stainless Steel
 Mid Plate: Stainless Steel
Plating
 Data Contact
 Underplating: 50µ" Min. Nickel
 Contact Plating: 1µ" Gold
 Solder Area: 80µ" Matte Tin
Shell
 Metallic Shell: 50µ" Min. Nickel
 Cover Shell
 Metallic Shell: 80µ" Min. Nickel
 Inner Ground Cover Shell
 Metallic Shell: 50µ" Min. Nickel
Electrical
 Voltage Rating: 20V DC
 Current Rating: Vbus pins collectively 5.00A, GND pins collectively 6.25A, B5 pin 1.25A, Other pins 0.25A per pin.
 Contact Resistance: 40mΩ Max.
 Insulation resistance: 100 MΩ MIN.
 Dielectric withstanding voltage: 100V AC/Minute
Mechanical
 Durability: 10,000 cycles
 Mating Force: 5 to 20N
 Unmating Force: 8 to 20N (post test)



USB31-TYPEC-33X41-XFS

- 1: Tray 2: Tape reel
- 41: IP67
- 52: IP54
- 53: 不防水
- 1: G/F 2: 5u" 3: 10u"
- 4: 15u" 5: 30u"

广东星坤科技股份有限公司

生效	日期
ΔX	ΔX
ΔX	ΔX
MARK	DESCRIPTION
文件工程	REVISIONS
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DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	USB 3.1 TYPE
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT
			1.0g
			SHEET
			1/1
			REVISION
			A0